

AMENDMENTS TO THE CLAIMS

The claims in this listing will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Currently Amended) A photosensitive composition ~~characterized by~~ comprising:

from 30 to 90 percent by weight of an epoxy compound (a) having two or more epoxy groups in a molecule;

from 0.1 to 40 percent by weight of a polynuclear phenol compound (b) comprising three to five phenolic aromatic rings, wherein either of the ortho positions of each hydroxyl group is not substituted with any of a methylol group, or an alkyl group or cycloalkyl group having four or more carbon atoms and each of two or more of the phenolic aromatic rings has at least one unsubstituted position ortho to the hydroxyl group; and

from 0.1 to 10 percent by weight of an energy beam-sensitive cationic polymerization initiator (c); and

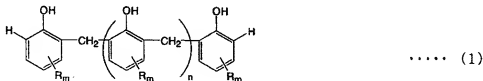
from 1 to 60 percent by weight of a hydroxyl group-containing compound (d) having one or more hydroxyl groups and one or more of at least one of a vinyl ether group and an oxetanyl group having cationic polymerizability in a molecule.

2. (Canceled)

3. (Previously Presented) The photosensitive composition according to claim 1, wherein the epoxy groups of the epoxy compound (a) are alicyclic epoxy groups.

4. (Currently Amended) The photosensitive composition according to claim 1, wherein the polynuclear phenol compound (b) comprises various a plurality of polynuclear phenol compounds (c) represented by general formula (1):

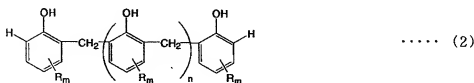
{Formula 1}



[[[]] wherein R denotes a C₁-C₅ alkyl group, a C₅-C₁₀ cycloalkyl group, a C₁-C₅ alkoxy group, a halogen atom, a hydroxyl group, an aryl group or an aralkyl group; all of the plurality of R in the formula each may be the same or different; m is an integer from 0 to 3; and n is an integer from 1 to 3 []]; and

further contains various a plurality of polynuclear phenol compounds (f) represented by general formula (2):

{Formula 2}

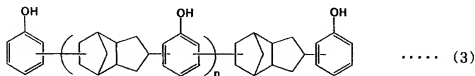


[[[]] wherein R denotes a C₁-C₅ alkyl group, a C₅-C₁₀ cycloalkyl group, a C₁-C₅ alkoxy group, a halogen atom, a hydroxyl group, an aryl group or an aralkyl group; all of the plurality of R in the formula each may be the same or different; m is an integer from 0 to 3; and n is an integer of 0 or 4 or more []],

the percentage of the plurality of polynuclear phenol compounds (e) relative to ~~[[the]]~~ a total of the plurality of polynuclear phenol compounds (e) and the plurality of polynuclear phenol compounds (f) being 40 percent by weight or more.

5. (Currently Amended) The photosensitive composition according to claim 1, wherein the polynuclear phenol compound (b) comprises ~~various~~ a plurality of polynuclear phenol compounds (g) represented by ~~general~~ formula (3):

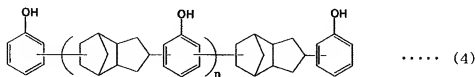
[Formula 3]



[[[]]] wherein n is an integer from 1 to 3 [[D]]; and

further contains ~~various~~ a plurality of polynuclear phenol compounds (h) represented by ~~general~~ formula (4):

[Formula 4]



[[[]]] wherein n is an integer of 0 or 4 or more [[D]],

the percentage of the plurality of polynuclear phenol compounds (g) relative to the total of the plurality of polynuclear phenol compounds (g) and the plurality of polynuclear phenol compounds (h) being 40 percent by weight or more.

6. (Currently Amended) A cured product obtained by irradiating the photosensitive composition according to claim 1 with an active beam ~~and optionally heating the irradiated composition.~~

7. (Previously Presented) A photosensitive adhesive comprising the photosensitive composition according to claim 1.

8. (Previously Presented) A photosensitive coating material comprising the photosensitive composition according to claim 1.

9. (Previously Presented) A photosensitive ink jet ink comprising the photosensitive composition according to claim 1 and a coloring agent.

10. (Currently Amended) A cured product obtained by irradiating the photosensitive material according to claim 7 with an active beam ~~and optionally heating the irradiated material.~~

11. (Original) A flat panel display produced by using the photosensitive adhesive according to claim 7 as a sealer.

12. (Original) The flat panel display according to claim 11, wherein the flat panel display is an organic electroluminescent display.

13. (Previously Presented) The photosensitive coating material according to claim 8, further comprising an alkoxysilane.

14. (Previously Presented) The photosensitive coating material according to 13, wherein the alkoxysilane is tetraethoxysilane.

15. (New) The cured product according to claim 6 further comprising heating the photosensitive composition to obtain the cured product.

16. (New) The cured product according to claim 10 further comprising heating the photosensitive material to obtain a cured product.

17. (New) A cured product obtained by irradiating the photosensitive composition according to claim 3 with an active beam.

18. (New) A photosensitive adhesive comprising the photosensitive composition according to claim 3.

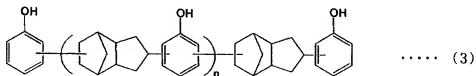
19. (New) A photosensitive composition comprising:

from 30 to 90 percent by weight of an epoxy compound (a) having two or more epoxy groups in a molecule;

from 0.1 to 40 percent by weight of a polynuclear phenol compound (b) comprising three to five phenolic aromatic rings, wherein either of the ortho positions of each hydroxyl group is not substituted with any of a methylol group, or an alkyl group or cycloalkyl group having four or more carbon atoms and each of two or more of the phenolic aromatic rings has at least one unsubstituted position ortho to the hydroxyl group; and

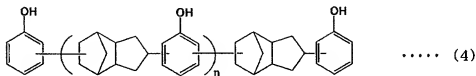
from 0.1 to 10 percent by weight of an energy beam-sensitive cationic polymerization initiator (c), and

wherein the polynuclear phenol compound (b) comprises a plurality of polynuclear phenol compounds (g) represented by formula (3):



wherein n is an integer from 1 to 3; and

further contains a plurality of polynuclear phenol compounds (h) represented by formula (4):



wherein n is an integer of 0 or 4 or more,

the percentage of the plurality of polynuclear phenol compounds (g) relative to the total of the plurality of polynuclear phenol compounds (g) and the plurality of polynuclear phenol compounds (h) being 40 percent by weight or more.

20. (New) A photosensitive ink jet ink comprising a photosensitive composition and a coloring agent, the photosensitive composition comprising:

from 30 to 90 percent by weight of an epoxy compound (a) having two or more epoxy groups in a molecule;

from 0.1 to 40 percent by weight of a polynuclear phenol compound (b) comprising three to five phenolic aromatic rings, wherein either of the ortho positions of each hydroxyl group is not substituted with any of a methylol group, or an alkyl group or cycloalkyl group having four or more carbon atoms and each of two or more of the phenolic aromatic rings has at least one unsubstituted position ortho to the hydroxyl group; and

from 0.1 to 10 percent by weight of an energy beam-sensitive cationic polymerization initiator (c).